Special Issue

RF/MM-Wave/THz Integrated Circuit Design for 5G/6G, Artificial Intelligence, Internet-of-Things, and Future Computing Applications

Message from the Guest Editors

As the physical, digital, and biological worlds continue to converge, new technologies and platforms are changing our lives and reshaping our societies and economies. The exponential growth of advanced technologies such as 5G/6G, artificial intelligence (AI), the Internet of things (IoT), and future computing (e.g., DNA computing, neuromorphic computing, quantum computing, and optical or photonic computing) is pushing semiconductor technology to its limits. Also, future networks will become extremely heterogenous, which brings great challenges to wireless connection, spectrum share, as well as data fusion.

Therefore, the next generation of wireless communication and semiconductor technology is expected to meet the demands of various challenging use cases that cover a wide range of new applications from 5G/6G communications, mobile computing, AI, and advanced Internet of things to big data, cloud, and edge computing.

This Special Issue aims to discuss open problems and present new solutions that address the challenges of future communication systems, AI, ubiquitous connectivity, IoT networking, and RF/mm-wave/THz chip design.

Guest Editors

Prof. Dr. Kiat Seng Yeo

Dr. Nagarajan Mahalingam

Dr. Bo Wang

Deadline for manuscript submissions

closed (31 December 2024)

Electronics

an Open Access Journal by MDPI

Impact Factor 2.6
CiteScore 6.1

mdpi.com/si/176556

Electronics
Editorial Office
MDPI, Grosspeteranlage 5
4052 Basel, Switzerland
Tel: +41 61 683 77 34
electronics@mdpi.com

mdpi.com/journal/electronics

Electronics

an Open Access Journal by MDPI

Impact Factor 2.6
CiteScore 6.1

mdpi.com/journal/electronics

About the Journal

Message from the Editor-in-Chief

Electronics is a multidisciplinary journal designed to appeal to a diverse audience of research scientists, practitioners, and developers in academia and industry. The journal is devoted to fast publication of latest technological breakthroughs, cutting-edge developments, and timely reviews of current and emerging technologies related to the broad field of electronics. Experimental and theoretical results are published as regular peer-reviewed articles or as articles within Special Issues guestedited by leading experts in selected topics of interest.

Editor-in-Chief

Prof. Dr. Flavio Canavero
Department of Electronics and Telecommunications, Politecnico di Torino, 10129 Torino, Italy

Author Benefits

High Visibility:

indexed within Scopus, SCIE (Web of Science), CAPlus / SciFinder, Inspec, Ei Compendex and other databases.

Journal Rank:

JCR - Q2 (Engineering, Electrical and Electronic) / CiteScore - Q1 (Electrical and Electronic Engineering)

Rapid Publication:

manuscripts are peer-reviewed and a first decision is provided to authors approximately 16.8 days after submission; acceptance to publication is undertaken in 2.4 days (median values for papers published in this journal in the first half of 2025).

MDPI